



EtraLED-LUME-11080 Lumens Modular Passive Star LED Heat Sink Φ110mm

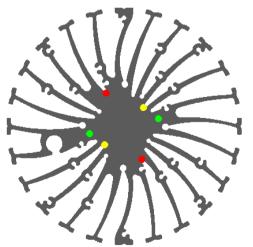
Features VS Benefits

- * The EtraLED-LUME-11080 Lumens Pin Fin LED Heat Sinks are specifically designed for luminaires using the Lumens LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 3000 to 7,200 lumen.
- * Thermal resistance range Rth 1.03°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Lumens Ergon COB series, and AC-ALL series LED engines.
- * Diameter 110.0mm standard height 50.0mm Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Lumens COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.





Lumens LED Modules directly Mounting Options Lumens Ergon COB_HO, COB_HO+, COB_HE Series :

Without the holders for the green indicator marks.

Direct mounting with machine screws M3x6.5mm

Lumens Ergon COB_HO, COB_HO+, COB_HE Series :

With the Zhaga Book 11 holders for the green indicator marks.

Direct mounting with machine screws M3x6.5mm

Lumens AC-ALL Series :

EDC/47C/10W/xxx/120V/B; EDC/47C/12W/xxx/120V/B; EDC/47C/10W/xxx/230V/A; EDC/47C/12W/xxx/230V/A;

With the Zhaga Book 3 holders for the red indicator marks. Direct mounting with machine screws M3x6.5mm

Please refer to the www.lumensleds.com data provided on the manual.



Mounting Options and Drawings & Dimensions

Example:EtraLED-LUME-11080-B-1,2

Example:EtraLED-LUME-110 1 - 2 -

mple:EtraLED-LUME-110

1 Height (mm)

Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

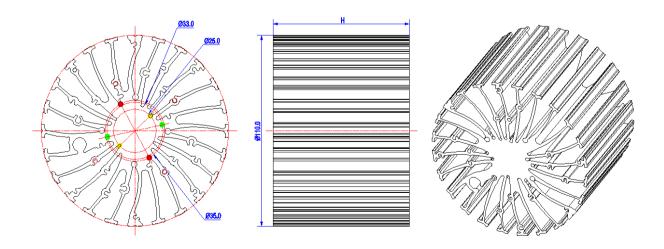
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

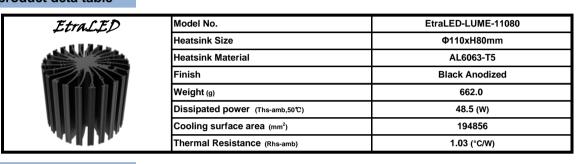
| MOUNTING OPTION | Module type | Holder NO. | THREAD | THREAD DEPTH | THREAD HOLE DISTANCE |
|-----------------|---------------------------|------------------------------|--------|-----------------|------------------------------------|
| 1 | Ergon COB (15.85×15.85) / | | М3 | 6.5mm | 22.0mm/ 2-@180° |
| 2 | Ergon COB (17.85×17.85) | / | | 6.5mm | 25.0mm/ 2-@180° (Zhaga book 11) |
| | Ergon COB (15.85×15.85) | BJB Holder 47.319.6104.50 | М3 | | |
| | | ldeal Holder 50-2001CR | | | |
| 3 | AC-ALL Series | Lumens | | 6.5mm | 35.0mm/ 2-@180° (Zhaga book 3) |
| | Ergon COB (17.85×17.85) | BJB Holder 47.319.2131.50 | M3 | | |
| | | ldeal Holder 50-2101CR | | | |







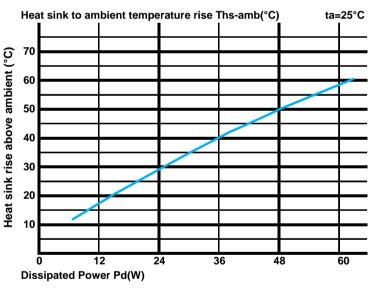
The product deta table



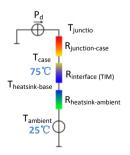
The thermal data table

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
- Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;

| Pd = Pe x (1-ηL) | | Heat sink to ambient thermal resistance Rhs-amb (°C/W) | Heat sink to ambient temperature rise Ths-amb (°C) | |
|------------------------|------|--|--|--|
| | | EtraLED-LUME-11080 | | |
| Dissipated Power Pd(W) | 12.0 | 1.33 | 16.0 | |
| | 24.0 | 1.21 | 29.0 | |
| | 36.0 | 1.11 | 40.0 | |
| | 48.0 | 1.03 | 49.5 | |
| | 60.0 | 0.95 | 57.0 | |



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:module} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.1-0.15 mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface}(TIM)$ ["C,M"], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ ["C,M"], and the ambient temperature is $T_{ambient}$ ["C].
- *Thermal resistances outside the package $R_{interface \, (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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